

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT5204749

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT
NATURE OF CONVEYANCE:	Corrective Assignment to correct the ADDRESS OF THE ASSIGNEE previously recorded on Reel 046589 Frame 0269. Assignor(s) hereby confirms the ASSIGNMENT.
CONVEYING PARTY DATA	
Name	Execution Date
HIKARU MIZUMURA	07/23/2018
TOSHIO ODA	07/23/2018
TOMOKAZU MATSUE	07/24/2018
KUMI INOUE	07/24/2018
RECEIVING PARTY DATA	
Name:	SEIKAGAKU CORPORATION
Street Address:	6-1, MARUNOUCHI 1-CHOME, CHIYODA-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	100-0005
Name:	TOHOKU UNIVERSITY
Street Address:	2-1-1, KATAHIRA, AOBA-KU
City:	SENDAI-SHI, MIYAGI
State/Country:	JAPAN
Postal Code:	980-8577
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16076614
CORRESPONDENCE DATA	
Fax Number:	(312)616-5700
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	(312) 616-5600
Email:	mgreer@leydig.com
Correspondent Name:	JOHN KILYK, JR.
Address Line 1:	LEYDIG, VOIT & MAYER, LTD.
Address Line 2:	TWO PRUDENTIAL PLAZA, SUITE 4900
Address Line 4:	CHICAGO, ILLINOIS 60601-6731

ATTORNEY DOCKET NUMBER:	739807
NAME OF SUBMITTER:	JOHN KILYK, JR.
SIGNATURE:	/John Kilyk, Jr./
DATE SIGNED:	10/24/2018
Total Attachments: 6 source=CorrectiveAssignmentSubmission#page1.tif source=CorrectiveAssignmentSubmission#page2.tif source=CorrectiveAssignmentSubmission#page3.tif source=CorrectiveAssignmentSubmission#page4.tif source=CorrectiveAssignmentSubmission#page5.tif source=CorrectiveAssignmentSubmission#page6.tif	

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
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<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>HIKARU MIZUMURA</td><td>07/23/2018</td></tr><tr><td>TOSHIO ODA</td><td>07/23/2018</td></tr><tr><td>TOMOKAZU MATSUE</td><td>07/24/2018</td></tr><tr><td>KUMI INOUE</td><td>07/24/2018</td></tr></tbody></table>	Name	Execution Date	HIKARU MIZUMURA	07/23/2018	TOSHIO ODA	07/23/2018	TOMOKAZU MATSUE	07/24/2018	KUMI INOUE	07/24/2018	
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Address Line 4:	CHICAGO, ILLINOIS 60601-6731										

PATENT**REEL 047305 FRAME 0094**

ATTORNEY DOCKET NUMBER:	739807
NAME OF SUBMITTER:	JOHN KILYK, JR.
Signature:	/John Kilyk, Jr./
Date:	08/08/2018
Total Attachments: 4 source=Assignment#page1.tif source=Assignment#page2.tif source=Assignment#page3.tif source=Assignment#page4.tif	
RECEIPT INFORMATION EPAS ID: PAT5089134 Receipt Date: 08/08/2018	

PATENT

REEL 047305 FRAME 0095

ASSIGNMENT

WHEREAS, I/WE

(1) Hikaru MIZUMURA, c/o SEIKAGAKU CORPORATION, 6-1, Marunouchi 1-chome, Chiyoda-ku, Tokyo 100-0005, Japan,

(2) Toshio ODA, c/o SEIKAGAKU CORPORATION, 6-1, Marunouchi 1-chome, Chiyoda-ku, Tokyo 100-0005, Japan

(3) Tomokazu MATSUE, c/o TOHOKU UNIVERSITY, 2-1-1, Katahira, Aoba-ku, Sendai-shi, Miyagi 980-8577, Japan, and

(4) Kumi INOUE, c/o TOHOKU UNIVERSITY, 2-1-1, Katahira, Aoba-ku, Sendai-shi, Miyagi 980-8577, Japan

hereinafter referred to as Assignor, have invented a certain invention entitled:

ELECTROCHEMICAL MEASUREMENT USING PHENYLENEDIAMINE DERIVATIVE

for which International Patent Application No. PCT/JP2017/005514 has been filed on February 15, 2017, and

WHEREAS,

(1) SEIKAGAKU CORPORATION of 6-1, Marunouchi 1-chome, Chiyoda-ku, Tokyo 100-0005, Japan, and

(2) TOHOKU UNIVERSITY of 2-1-1, Katahira, Aoba-ku, Sendai-shi, Miyagi 980-8577, Japan,

hereinafter jointly referred to as Assignee, are desirous of acquiring the entire U.S. right, title, and interest of Assignor in, to, and under the invention and the referenced International Patent Application, including the entire right, title, and interest of Assignor in, to, and under the U.S. national phase thereof, filed on August 8, 2018, as U.S. Patent Application No. 16/076,614,

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged,

Assignor assigns and transfers to Assignee the entire U.S. right, title, and interest of Assignor in, to, and under the invention, the referenced International Patent Application and U.S. national phase thereof, and other such U.S. patent applications (e.g., continuations, continuations-in-part, divisionals, reissues, and reexaminations) that may be filed in the U.S. with a claim of priority to the referenced International Patent Application and/or the U.S. national phase application thereof, as well as U.S. patents that may issue thereon and that may

be modified as the result of applicable procedures (e.g., supplemental examinations, ex parte reexaminations, inter partes reexaminations, inter partes reviews, and post-grant reviews),

Assignor conveys to the Assignee the right to make applications in Assignee's own behalf for protection of the invention in the U.S. and to claim priority in the U.S. to the aforementioned patent applications and any priority documents referenced therein under the Patent Cooperation Treaty, the Paris Convention, and any other international arrangements,

Assignor will not execute any writing or do any act conflicting with the terms of this assignment,

Assignor will at any time upon request, without further or additional consideration, but at the expense of the Assignee, execute such additional assignments and other writings and do such additional acts as the Assignee may deem necessary or desirable to pursue the U.S. patent applications identified herein, including, but not limited to, rendering all necessary assistance in making applications for and obtaining patents that may issue thereon in the U.S. on the invention, and in enforcing any rights accruing as a result of such U.S. applications or patents, by, for example, executing statements and other affidavits,

Assignor and Assignee agree the terms of this assignment shall bind, and inure to the benefit of, the legal representatives, successors, and assigns of all parties hereto,

Assignor authorizes Assignee to insert in this assignment the number and filing date of the U.S. patent application if the number and filing date of the U.S. patent application are not recited herein at the time of execution of this assignment by any or all of the parties hereto,

Assignor and Assignee agree that U.S. law governs this assignment, and

Assignee acknowledges and accepts this assignment.

IN WITNESS WHEREOF, Assignor has hereunder set his/her hand on the date shown below.

Date July 23, 2018

Hikaru Mizumura
Assignor: Hikaru MIZUMURA

Date July 23, 2018

Toshio Oda
Assignor: Toshio ODA

Date _____

Assignor: Tomokazu MATSUE

Date _____

Assignor: Kumi INOUE

ASSIGNMENT

WHEREAS, I/We

- (1) Hikaru MIZUMURA, c/o SEIKAGAKU CORPORATION, 6-1, Marunouchi 1-chome, Chiyoda-ku, Tokyo 100-0005, Japan,
- (2) Toshio ODA, c/o SEIKAGAKU CORPORATION, 6-1, Marunouchi 1-chome, Chiyoda-ku, Tokyo 100-0005, Japan
- (3) Tomokazu MATSUE, c/o TOHOKU UNIVERSITY, 2-1-1, Katahira, Aoba-ku, Sendai-shi, Miyagi 980-8577, Japan, and
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hereinafter jointly referred to as Assignee, are desirous of acquiring the entire U.S. right, title, and interest of Assignor in, to, and under the invention and the referenced International Patent Application, including the entire right, title, and interest of Assignor in, to, and under the U.S. national phase thereof, filed on August 8, 2018, as U.S. Patent Application No. 16/076,614,

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged,

Assignor assigns and transfers to Assignee the entire U.S. right, title, and interest of Assignor in, to, and under the invention, the referenced International Patent Application and U.S. national phase thereof, and other such U.S. patent applications (e.g., continuations, continuations-in-part, divisionals, reissues, and reexaminations) that may be filed in the U.S. with a claim of priority to the referenced International Patent Application and/or the U.S. national phase application thereof, as well as U.S. patents that may issue thereon and that may

be modified as the result of applicable procedures (e.g., supplemental examinations, ex parte reexaminations, inter partes reexaminations, inter partes reviews, and post-grant reviews),

Assignor conveys to the Assignee the right to make applications in Assignee's own behalf for protection of the invention in the U.S. and to claim priority in the U.S. to the aforementioned patent applications and any priority documents referenced therein under the Patent Cooperation Treaty, the Paris Convention, and any other international arrangements,

Assignor will not execute any writing or do any act conflicting with the terms of this assignment,

Assignor will at any time upon request, without further or additional consideration, but at the expense of the Assignee, execute such additional assignments and other writings and do such additional acts as the Assignee may deem necessary or desirable to pursue the U.S. patent applications identified herein, including, but not limited to, rendering all necessary assistance in making applications for and obtaining patents that may issue thereon in the U.S. on the invention, and in enforcing any rights accruing as a result of such U.S. applications or patents, by, for example, executing statements and other affidavits,

Assignor and Assignee agree the terms of this assignment shall bind, and inure to the benefit of, the legal representatives, successors, and assigns of all parties hereto,

Assignor authorizes Assignee to insert in this assignment the number and filing date of the U.S. patent application if the number and filing date of the U.S. patent application are not recited herein at the time of execution of this assignment by any or all of the parties hereto,

Assignor and Assignee agree that U.S. law governs this assignment, and

Assignee acknowledges and accepts this assignment.

IN WITNESS WHEREOF, Assignor has hereunder set his/her hand on the date shown below.

Date _____

Assignor: Hikaru MIZUMURA

Date _____

Assignor: Toshio ODA

Date 24 July, 2018

Assignor: Tomokazu MATSUE

Date 24 July, 2018

Assignor: Kumi INOUE